

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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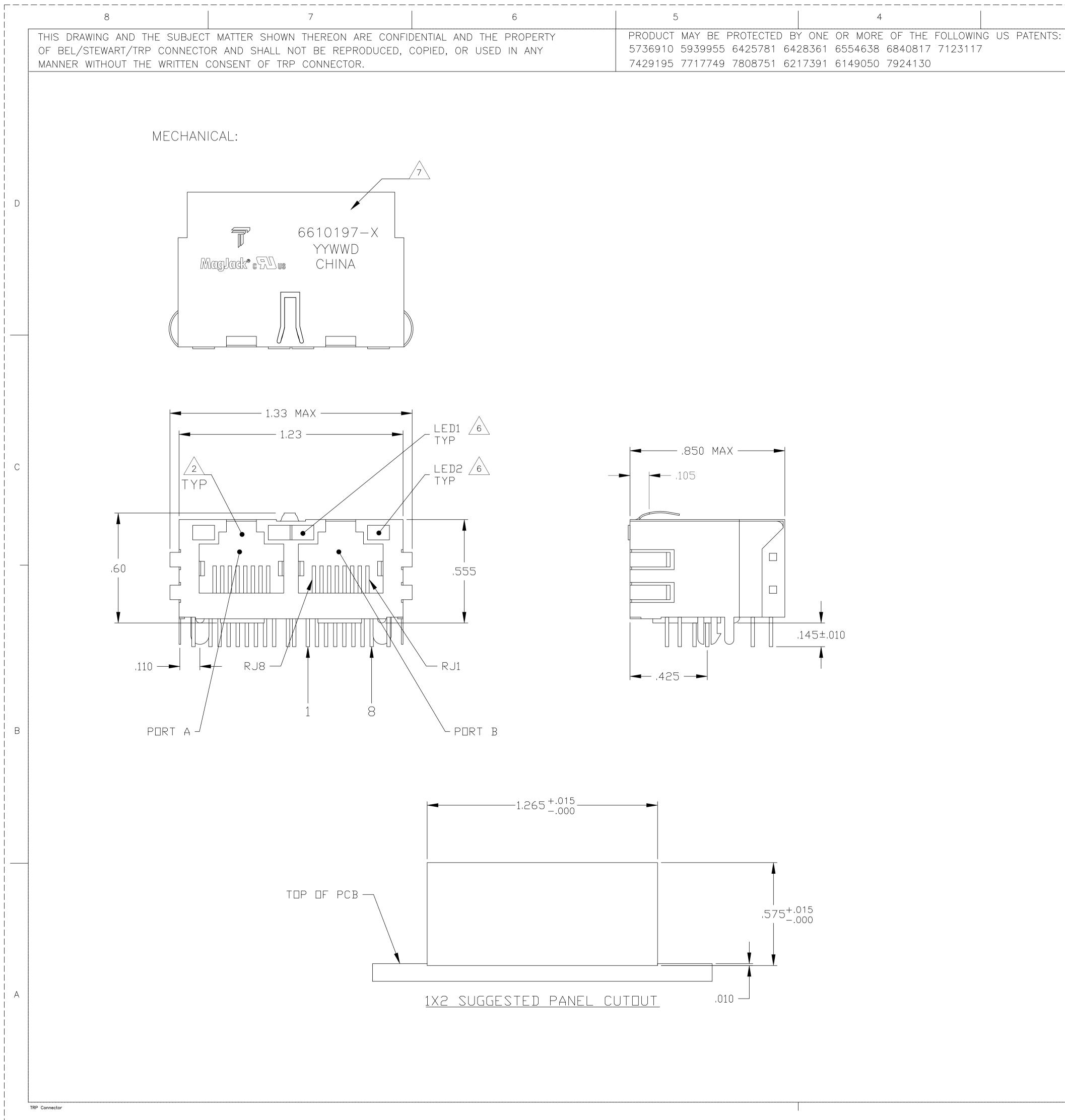
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REVISIONS 08JAN2015 DZ | TL D EC-1411035 COMPANY LOGO CHANGE

MATERIALS:
-HOUSING - THERMOPLASTIC PET POLYESTER FLAMMABILITY RATING UL 94V-0. -SHIELD - .010" THICK, C26800 BRASS PREPLATED WITH 30 μ INCH MIN SEMI-BRIGHT NICKEL. SOLDER TABS POST DIPPED WITH 100 μ INCH MIN SAC SOLDER. -MOD JACK CONTACTS - 0.0157 X 0.018" PHOSPHOR BRONZE, 50µINCH MIN OVERALL NICKEL UNDERPLATE WITH SELECT 50µINCH MIN HARD GOLD FINISH PLATE. SOLDERTAILS WITH 100 µINCH MIN MATTE TIN AND/OR SAC SOLDER DIP. -LIGHT EMITTING DIODE(LED) - DIFFUSED EPOXY LENS, .020" X .020" CARBON STEEL WIREFRAME LEADS PRE-PLATED WITH 80 μ INCH SILVER OVER 40 μ INCH NICKEL UNDERPLATE OVER 40 μ INCH COPPER UNDERPLATE. POST-PLATED WITH 100 μ IN MIN MATTE TIN AND/OR SAC SOLDER DIP OR PURE TIN SOLDER DIP.



2 RJ45 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUB PART F.

3 MAGNETICS

-IMPEDANCE: 100 OHMS -TURNS RATIO (CHIP:CABLE): TX = 1:1, RX = 1:1

-OPEN CIRCUIT INDUCTANCE (OCL): 350 µH MIN @100kHz, 0.1VRMS, 8mADC BIAS FROM -40°C TO +85°C, TX AND RX -PERFORMANCE @ 25°C: INSERTION LOSS (IL): 1.1dB MAX FROM 0.5MHz TO 100MHz

RETURN LOSS (RL): 18dB MIN FROM 0.5MHZ TO 30MHz 18-20LOG(f/30)dB MIN FROM 30.1MHz TO 60MHz 12dB MIN FROM 60.1MHz TO 80MHz CROSSTALK ATTENUATION: 35dB MIN FROM 0.5MHz TO 40MHz

33-20*LOG(f/50)dB MIN FROM 40.1MHz TO 100MHz COMMON MODE REJECTION RATIO (CMRR): 30dB MIN FROM 0.5MHz TO 100MHz -ISOLATION VOLTAGE: COMPLIES WITH IEEE802.3 2002, PARA 23.5.1.1, ITEM b.

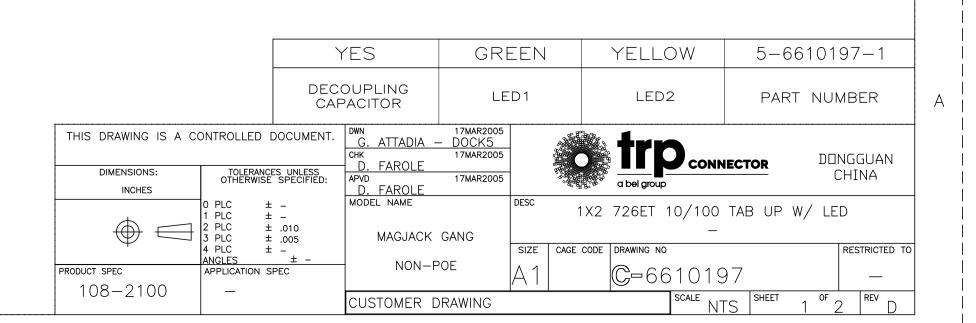
4. OPERATING TEMPERATURE: FROM -40°C TO +85°C

5\ INDICATED CONNECTIONS ARE FOR NIC CONFIGURATION. THE MAGNETICS ARE SYMMETRICAL AND SUPPORT AUTO-MDI/MDIX.

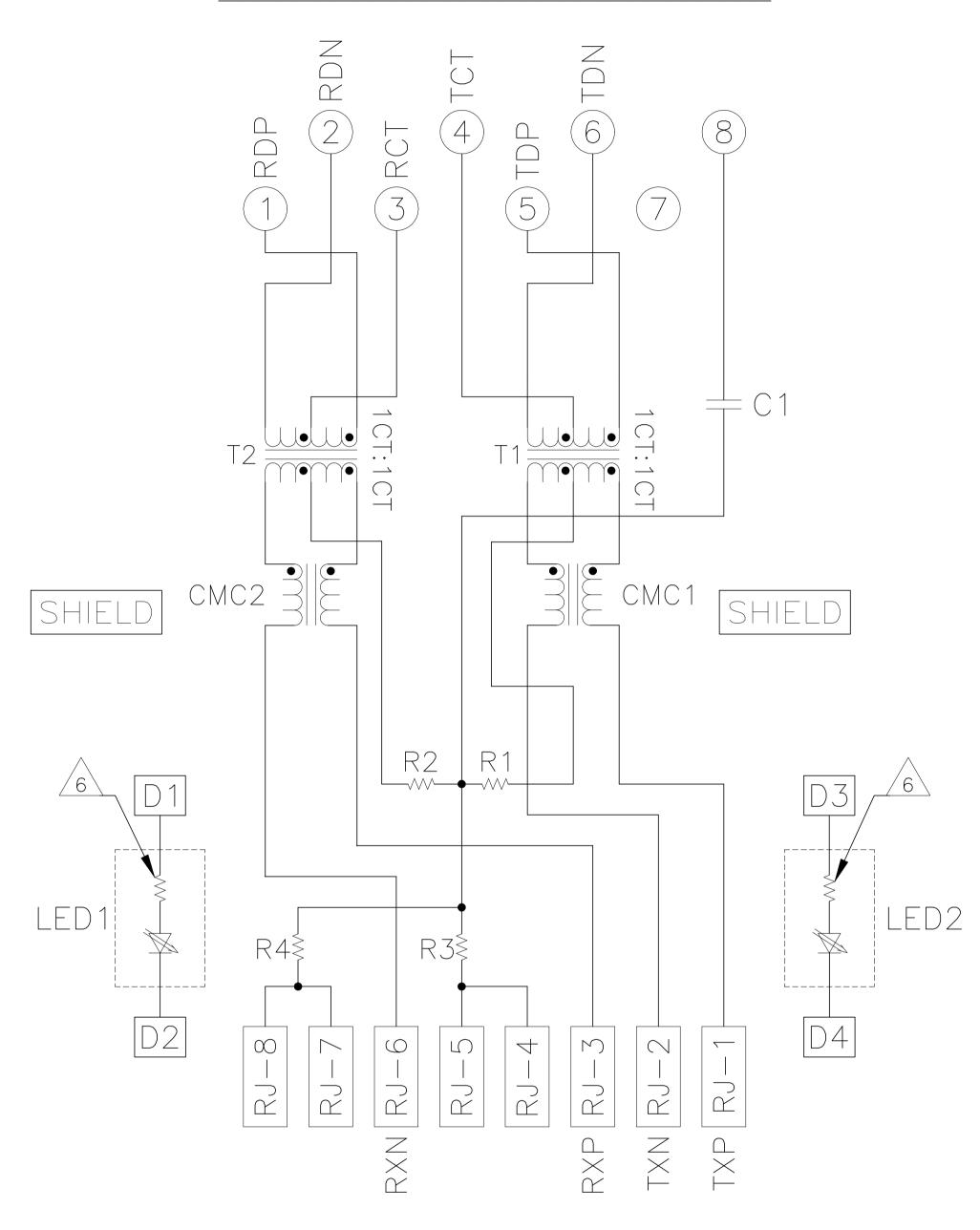
6 LEDS WITH BUILT-IN RESISTOR

 $\mathring{}$ LEDS ARE DRIVEN WITH 5V VOLTAGE AND THE MAX OPERATING CURRENT IS 20mA. LED COLOR: DOMINANT WAVELENGTH (AD): GREEN 568 nm TYP @ VF=5V FORWARD CURRENT (IF): GREEN 12mA TYP @ VF=5V DOMINANT WAVELENGTH (AD): YELLOW 588 nm TYP @ VF=5V FORWARD CURRENT (IF): YELLOW 13mA TYP @ VF=5V

8. THE PART IS RECOMMENDED FOR WAVE SOLDERING PROCESS, PREHEAT TEMPERATURE IS 120°C TO 160°C, 120 SECONDS TO 180 SECONDS, PEAK WAVE SOLDERING TEMPERATURE IS 260°C MAX, 10 SECONDS MAX.

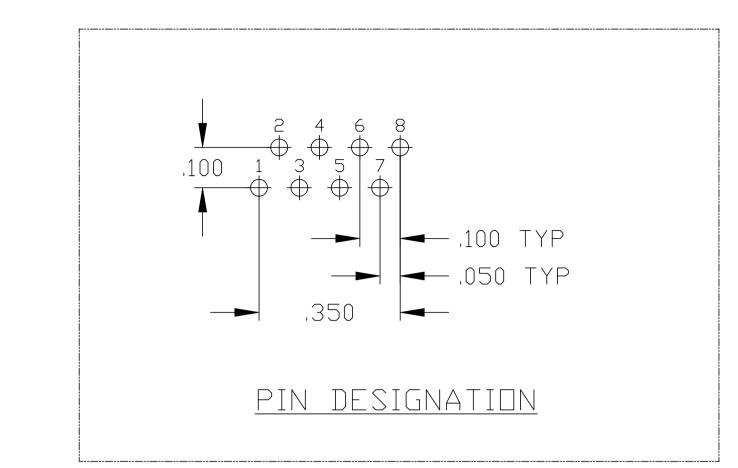


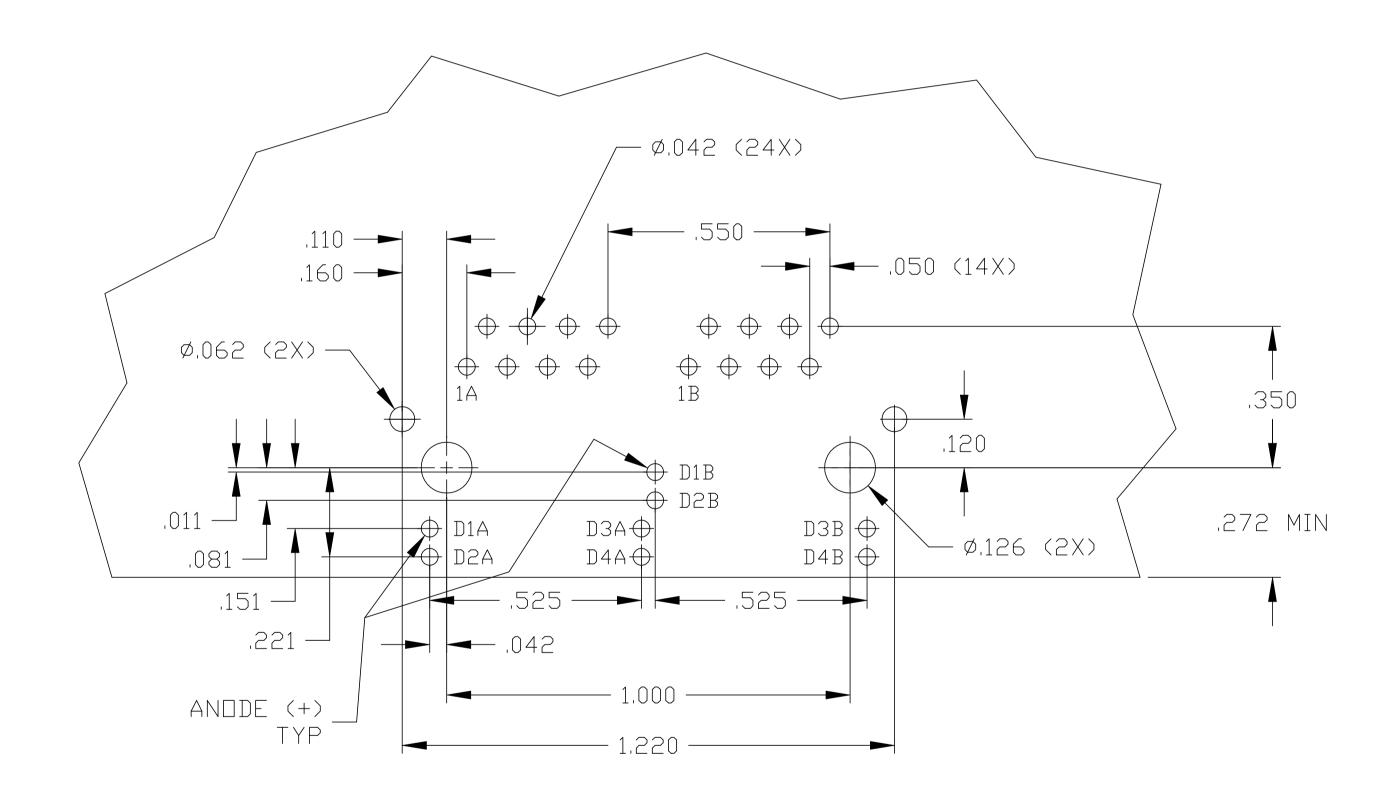




C1 = 1000pF, 2KV CAPACITOR

R1-R4 = 75 OHMS, 1/16 W RESISTORS





SUGGESTED PCB LAYOUT (Component Side)

